



## Product Change Notification - LIAL-25FTVP919

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**Date:**

06 Nov 2019

**Product Category:**

Others; PoE PSE

**Affected CPNs:****Notification subject:**

CCB 4000 Final Notice: Implement Packing Changes for selected Microsemi PoE products

**Notification text:****PCN Status:**

Final notification.

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

Note 1: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Note 2: As part of the integration process additional products may be identified that were not part of the original list.

**Description of Change:**

Implement Packing Changes for selected Microsemi PoE products within the Microsemi subsidiaries Microsemi Solutions Sdn.Bhd. which includes formerly Power over Ethernet.

Change in Tray/Reel/Bag

Change in Packing Method

**Pre Change:**

Using Microsemi's packing process.

**Post Change:**

Using Microchip's packing process.

**Pre and Post Change Summary:**

Details		PRE-CHANGE (MSCC)	POST CHANGE (Microchip)
Packing Details	Media	With Microsemi media	With Microchip media
	Moisture Barrier Bag / Static Shield Bag	Without pre-printed MSL caution label on bag	With pre-printed MSL caution label on bag
	Method	Tray	With pink foam on tray
			Without pink foam on tray



	Reel	With bubble sheet on reel	Without bubble sheet on reel
<b>Material</b>		MBB no Desiccant SSB + Desiccant	MSL1 product - use of static sensitive bag (SSB) without desiccant and HIC
<b>Desiccant</b>		1, or 2 desiccants per bag depending on packaging size	2 desiccants per bag for all products
<b>Humidity Indicator Card (HIC)</b>		Cobalt Dichloride free or Cobalt free	Cobalt free
<b>Tray Inner Carton</b>		See attached Pre and Post Changes	

Note: Please see attached file "packing pre and post changes" to view the changes documented above.

#### Impacts to Data Sheet:

None

#### Change Impact:

None.

#### Reason for Change:

To improve productivity by standardizing the packing method as part of the integration of Microsemi and Microchip.

#### Change Implementation Status:

In Progress

#### Earliest Implementation Date:

December 06, 2019

**Note:** The earliest implementation date is the earliest date that we may implement any combination of the changes listed in this PCN as we will not implement any of the proposed changes prior to this date. After the earliest implementation date these changes may occur to any product over the course of many months depending on inventory levels and business conditions.

#### Time Table Summary:

	November 2019					December 2019				
Workweek	44	45	46	47	48	49	50	51	52	53
Final PCN Issue Date		X								
Estimated Implementation Date						X				

#### Method to Identify Change:



Traceability, packing material

**Revision History:**

**November 06, 2019:** Issued Final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_LIAL-25FTVP919\\_Pre and Post changes.pdf](#)

[Frequently Asked Questions Microsemi November.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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